3D Packaging&IntegrationTaiwan TC Chapter

Meeting Summary and Minutes

Taiwan Summer Standards Meeting 2025

Thursday, August 14, 2025. 10:30–12:00

Official Virtual TC Chapter Meeting

TC Chapter Announcements

Next TC Chapter Meeting

TBD

Official Virtual Meeting, Hsinchu, Taiwan

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: Wendy Chen (KYEC)/ Roger Hwang (ASE)/ Jerry, C.H. Wang (ITRI)

SEMI Staff: *Cheryl Chuang/Nick Chen*

Company	*Last*	*First*	*Company*	*Last*	*First*
ASE	Yang	Jeffrey	AllRing-Tech	CHENG	KUAN LIN
Gudeng	Huang	Tim	OmniMeasure	Chen	Arthur
JABON	Lin	Paul	TSMC	Chen	Gary
JABON	WU	CHEN YI	SEMI Japan	Yoshida	Akiko
TSMC	Wang	Hao-Ren	AllRing-Tech	CHANG	WEI YANG
AllRing-Tech	Chang	Ryan	TSMC	Cheng	Y.R.
Delta	WANG	KAR	Micron	Nian	Xanxus
ITRI	Lee	Liheng	TSMC	Wang	Jhe-Hong
TSMC	Lin	Yu-Tsen	TSMC	Chou	Eason
AllRing-Tech	Chiang	Cellin	KLA	Chen	Allen
TSMC	Hsieh	Yun Ju	Acteon NEXT LLC	Komatsu	Shoji

Table 2 Leadership Changes

WG/TF/SC/TC Name	*Previous Leader*	*New Leader*
None		

Table 3 Committee Structure Changes

Previous WG/TF/SC Name	*New WG/TF/SC Name or Status Change*
None	3D Packaging Smart Manufacturing Task Force

Table 4 Ballot Results

Document #	*Document Title*	*Committee Action*
None		

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Activities Approved by the GCS between meetings of the TC Chapter

#	*Type*	*SC/TF/WG*	*Details*
None			

Table 6 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	*Type*	*SC/TF/WG*	*Details*
-	TFOF	3D Packaging Smart Manufacturing Task Force	TC Chapter approved new TFOF of 3D Packaging Smart Manufacturing Task Force
7391	SNARF	3D Packaging Smart Manufacturing Task Force	TC Chapter approved SNARF titled “Guide for Trays Accommodating 380x380mm2 IC Packages” developed by 3D Packaging Smart Manufacturing Task Force
-	Type ll Liaison proposal	3D Packaging Smart Manufacturing Task Force	TC Chapter approved that 3D Packaging Smart Manufacturing Task Force will pursue a Type II Liaison with JEDEC.

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:
http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF

Table 7 Authorized Ballots

#	*When*	*TF*	*Details*
None			

Table 8 SNARF(s) Granted a One-Year Extension

#	*TF*	*Title*	*Expiration Date*
None			

Table 9 SNARF(s) Abolished

#	*TF*	*Title*
None		

Table 10 Standard(s) to receive Inactive Status

Standard Designation	*Title*
None	

Table 11 New Action Items

Item #	*Assigned to*	*Details*
	3D Packaging Smart	3D Packaging Smart Manufacturing Task Force will pursue a Type II Liaison with JEDEC.

	Manufacturing Task Force	

Table 12 Previous Meeting Action Items

Item #	*Assigned to*	*Details*
None		

1 Welcome, Reminders, and Introductions

Committee Chairs Wendy Chen (KYEC) called the meeting to order at 10:30. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: Required Element Nov 2020

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion: Approve previous meeting minute.
By / 2nd: Shoji Komatsu (Acteon NEXT LLC)/ LIN YU TSEN (TSMC)
Discussion: None
Vote: 9-0 in favor. Motion passed

Attachment: 3D PI Taiwan Meeting Minutes_20220902_v2

3 Liaison Reports

3.1 Information & Control NA TC Chapter

- Nick Chen reported for the report Of note:

  Attachment: NA 3DP&I Liaison Report Feb2025 v2

3.2 Information & Control Japan TC Chapter

- Akiko Yoshida (SEMI Japan) reported for the report Of note:

Attachment: JA 3DP&I_Liaison Report_July 2025_R0

3.3 SEMI Staff Report

--Nick Chen gave the SEMI Staff Report Of note

SEMI Global 2025 Calendar of Events

- 2025 Critical Dates for SEMI Standards Ballots
- Promote SEMI 20 Under 40 in SEMICON Taiwan 2025

Attachment: 3D P&I Taiwan TC Staff Report_20250814

4 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document is provided under each ballot review section below.

None

5 Subcommittee and Task Force Reports

5.1 Testing Task Force

- No update.

5.2 Middle End Process Task Force

- No update.

6. Old Business

None

7. New Business

7.1 TC Chapter approved that 3D Packaging Smart Manufacturing Task Force will pursue a Type II Liaison with JEDEC.

Motion: Chih Hao Chen (TSMC)

2ND By: TZU TING CHOU (TSMC)

Discussion: None

Result: 8-Y 0-N Voting Result: Pass

7.2 TC Chapter approved new TFOF of 3D Packaging Smart Manufacturing Task Force.

Motion: Chih Hao Chen (TSMC)

2ND By: Shoji Komatsu (Acteon NEXT LLC)

Discussion: None

Result: 9-Y 0-N Voting Result: Pass

7.3 TC Chapter approved SNARF titled "Guide for Trays Accommodating 380x380mm2 IC Packages" developed by 3D Packaging Smart Manufacturing Task Force.

Motion: Chih Hao Chen (TSMC)

2ND By: Roger Hwang (ASE)

Discussion: None

Result: 11-Y 0-N Voting Result: Pass

8. Next Meeting and Adjournment

The next meeting is scheduled to be determined.

See http://www.semi.org/standards-events for the current list of events

Adjournment: 12:00

Respectfully submitted by:

Cheryl Chuang

Standards Coordinator

SEMI Taiwan
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Email: cchuang@semi.org

Minutes tentatively approved by:

Co-chair	Date Approved
Wendy Chen (KYEC)	Aug 18, 2025
Roger Hwang (ASE)	Aug 15, 2025
Jerry, C.H. Wang (ITRI)	

Table 13 Index of Available Attachments[#1]

Title	*Title*
1_ Required Element Nov 2020	5_3D P&I Taiwan TC Staff Report_20250814
2_3D PI Taiwan Meeting Minutes_20220902_v2	
3_ NA 3DP&I Liaison Report Feb2025 v2	
4_ JA 3DP&I_Liaison Report_July 2025_R0	

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.